TOSHIBA CMOS Linear Integrated Circuit Silicon Monolithic

# TCK22xxxG, TCK2065G, TCK1024G

#### Load Switch IC with Over current limited function

The TCK22xxxG, TCK2065G and TCK1024G are Load Switch ICs for power management with Over Current Limited function featuring low switch on resistance, ultra low quiescent current, high output current and wide input voltage operation. Switch ON resistance is only 31 m $\Omega$  at V $_{\rm IN}=5.0$  V, I $_{\rm OUT}=-0.15$  A load conditions. And these feature a thermal shut down function and output auto-discharge function.

This device is available in 0.4 mm pitch ultra small package WCSP6E (0.8 mm x 1.2 mm, t: 0.59 mm (max)). Thus this devices is ideal for portable applications that require high-density board assembly such as cellular phone.

#### **Feature**

- Over current limit function
   I<sub>CL</sub> = 400/740/1110/1540 mA (Option)
- Thermal Shutdown function
- Inrush current reduction
- Output auto-discharge function
- True Reverse Current Blocking function(Option)
- Under Voltage Lockout function(Option)
- Low ON resistance :

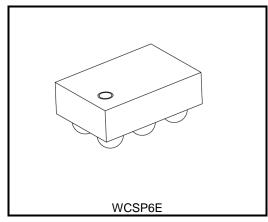
 $R_{ON}$  = 31 m $\Omega$  (typ.) at  $V_{IN}$  = 5.0 V,  $I_{OUT}$  = -0.15 A

 $R_{ON} = 40 \text{ m}\Omega$  (typ.) at  $V_{IN} = 3.3 \text{ V}$ ,  $I_{OUT} = -0.15 \text{ A}$ 

 $R_{ON}$  = 70  $m\Omega$  (typ.) at  $V_{IN}$  = 1.8 V,  $I_{OUT}$  = -0.15 A

 $R_{ON}$  = 141 m $\Omega$  (typ.) at  $V_{IN}$  = 1.2 V,  $I_{OUT}$  = -0.15 A

- Low Quiescent Current: IQ = 25 μA (typ.) at V<sub>IN</sub> = 5.5 V, I<sub>OUT</sub> = 0 mA
- Pull down connection between CONTROL and GND
- Ultra small package: WCSP6E (0.8mm x 1.2mm, t: 0.59mm(max))



Weight: 1 mg (typ.)



## **Function Table**

	Function						
Part number	Output current limit	True Reverse current blocking	Output auto-discharge	Under voltage lock out	Thermal shut down	Control pin polarity	Marking
TCK22946G	400 mA	Built in	Built in	Built in	Built in	Active High	1T
TCK22951G	740 mA	Built in	Built in	Built in	Built in	Active High	2T
TCK2065G	1110 mA	Built in	Built in	Built in	Built in	Active High	3T
TCK1024G	1540 mA	Built in	Built in	Built in	Built in	Active High	4T
TCK22891G	400 mA	N/A	Built in	N/A	Built in	Active High	5T
TCK22892G	740 mA	N/A	Built in	N/A	Built in	Active High	6T
TCK22893G	1110 mA	N/A	Built in	N/A	Built in	Active High	7T
TCK22894G	1540 mA	N/A	Built in	N/A	Built in	Active High	8T

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#### Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Input voltage	VIN	-0.3 to 6.0	V
Control voltage	Vст	-0.3 to 6.0	V
Output voltage	Vout	-0.3 to 6.0	V
Output current	Іоит	Internally limited	-
Power dissipation	Power dissipation PD 800		mW
Operating temperature range	T <sub>opr</sub>	-40 to 85	°C
Junction temeperature	Tj	150	°C
Storage temperature	T <sub>stg</sub>	−55 to 150	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note1: Rating at mounting on a board

Board material: Glass epoxy (FR4)

Board dimension: 40mm x 40mm (both sides of board), t=1.6mm

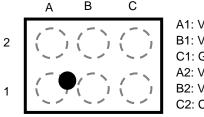
Metal pattern ratio: a surface approximately 50%, the reverse side approximately 50%

Through hole: diameter 0.5mm x 28

#### **Operating conditions**

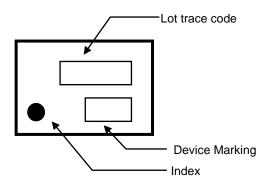
Characteristics	Symbol	Condition		Min	Max	Unit	
Input voltage	VIN	TCK22946G TCK22951G	_	1.1	5.5	5.5 V	
		Others	_	1.4	5.5		
Output voltage	Vout	_		_	VIN	V	
CONTROL High-level input voltage	\/	1.2V < V <sub>IN</sub> ≤ 5.5 V		1.0	_	V	
CONTROL High-level input voltage	VIH	1.1V ≤V <sub>IN</sub> ≤1.2 V		0.9	_	V	
CONTROL Low-level input voltage	VIL			_	0.4	V	

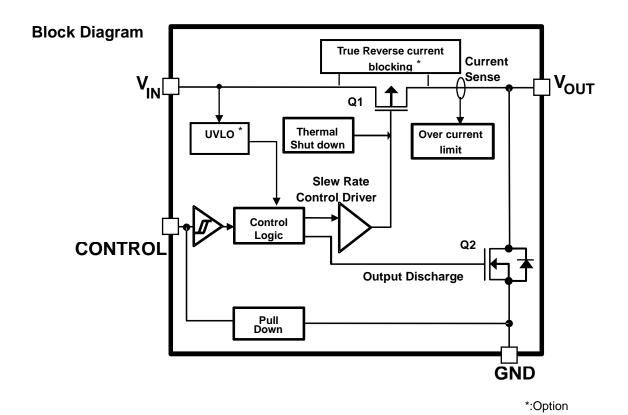
#### Pin Assignment(Top view)



A1: VOUT B1: VOUT C1: GND A2: VIN B2: VIN C2: CONTROL

#### Top marking





## **Operation logic table**

		TCK22946G	TCK22891G	
		TCK22951G	TCK22892G	
		TCK2065G	TCK22893G	
		TCK1024G	TCK22894G	
	Output Q₁	ON	ON	
Control	Discharge Q <sub>2</sub>	OFF	OFF	
"High"	Reverse current blocking	Active	ı	
	Output Q₁	OFF	OFF	
Control "Low"	Discharge Q <sub>2</sub>	ON	ON	
	Reverse current blocking	Active	_	



## **Electrical Characteristics**

## DC Characteristics (Ta = -40 to 85°C)

		Test Condition		Ta = 25°C			Ta = -40 to 85°C		
Characteristics	Symbol			Min	Тур.	Max	Min	Max	Unit
Quiescent current ( ON state)	IQ	IOUT = 0 mA	V <sub>IN</sub> = 1.1 V	_	16	1	_	_	μΑ
Quiescent current ( ON state)	iQ	1001 = 0111A	V <sub>IN</sub> = 5.5 V	_	25	-	_	50	μΑ
Quiescent current ( OFF state)	IQ(OFF)	VIN = 5.5 V, VO	UT = OPEN,	_	0.6	_	_	2.5	μА
Reverse blocking current	IRB	V <sub>OUT</sub> = 5.0 V, V <sub>IN</sub> = 0 V, RCB	active (Note 2)	_	0.01	ı	_	2	μА
Reverse blocking voltage threshold	V <sub>RB</sub>	Vout – Vin	(Note 2)	_	35		_	_	mV
Reverse blocking release voltage threshold	VRBR	VOUT – VIN (Note 2)		_	-15	_	_	_	mV
Under Voltage Lock Out (UVLO) rising threshold	Vuvl_ri	— (Note 2)		_	0.82	_	_	1.1	V
Under Voltage Lock Out (UVLO) falling threshold	VUVL_FA	_	(Note 2)	_	0.77		_	_	V
	Ron	I <sub>OUT</sub> = -0.15A	V <sub>IN</sub> = 5.0 V	_	31	ı	_	85	mΩ
			V <sub>IN</sub> = 3.3 V	_	40		_	95	
On resistance			V <sub>IN</sub> = 1.8 V	_	70	_	_	140	
			V <sub>IN</sub> = 1.2V	_	141	_	_	_	
			V <sub>IN</sub> = 1.1 V	_	179	_	_	_	
	lcL		TCK22946G	— 400	400	_	_	_	
		V <sub>IN</sub> = 5.5 V	TCK22891G						
Output United Output			TCK22951G TCK22892G	_	740	_	_	_	Δ
Output Limited Current			TCK2065G TCK22893G	_	1110	_	_	_	- mA
			TCK1024G TCK22894G	_	1540	_	_	_	
Output discharge on resistance	R <sub>SD</sub>	_		_	100	_	_	_	Ω

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Note 2: Only applies to the TCK22946G, TCK22951G, TCK2065G and TCK1024G



## AC Characteristics (Ta = 25°C)

 $V_{IN} = 5.0 V$ 

Characteristics	Symbol	Test Condition(Figure 1)	Min	Тур.	Max	Unit
Vout rise time	tr	$V_{\text{IN}}\text{=}~5.0~\text{V}$ , $R_{\text{L}}\text{=}~500\Omega$ , $C_{\text{L}}\text{=}0.1~\mu\text{F},$	_	50	_	μS
Vout fall time	tf	$V_{IN}$ = 5.0 $V$ , $R_L$ = 500 $\Omega$ , $C_L$ =0.1 $\mu F$ ,	_	50	_	μS
Turn on delay	ton	$V_{IN}$ = 5.0 V , $R_L$ = 500 $\Omega$ , $C_L$ =0.1 $\mu F$ ,	_	40	_	μS
Turn off delay	toff	$V_{\text{IN}}\text{=}~5.0~\text{V}$ , $R_{\text{L}}\text{=}~500\Omega$ , $C_{\text{L}}\text{=}0.1~\mu\text{F},$	_	10	_	μS

#### **AC Waveform**

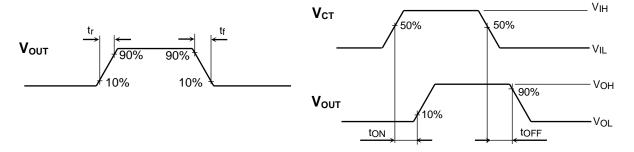


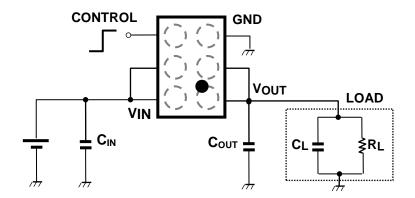
Figure 1 tr, tf, ton, toff Waveforms



#### **Application Note**

#### 1. Application circuit example (top view)

The figure below shows the recommended configuration.



Control Voltage	Output Voltage
HIGH	ON
LOW	OFF
OPEN	OFF

#### 1) Input and Output capacitor

An input capacitor (CIN) and an output capacitor (COUT) are necessary for the stable operation. And it is effective to reduce voltage overshoot or undershoot due to sharp changes in output current and also for improved stability of the power supply. When used, place CIN and COUT more than  $1.0\mu F$  as close to  $V_{IN}$  pin to improve stability of the power supply.

#### 2) Control pin

The CONTROL pin controls state of the switch, operated by the control voltage and Schmitt trigger. Also, pull down resistance equivalent to a few  $M\Omega$  is connected between CONTROL and GND, thus the load switch IC is in OFF state even when CONTROL pin is OPEN.

#### 2. Over current limit function

This device has a built-in fold-back type of Current-limiting Circuit. Around 15% or more derating against typical values is recommended for system design with enough margin.

#### 3. Thermal shutdown function

This device has a built-in Thermal shutdown circuit. If the junction temperature goes beyond 170°C (Typ.), thermal shutdown circuit operates and turns off power switch. When the junction temperature decreases lower than 150°C, the power switch is turned on due to hysteresis. This operation is repeated as long as the junction temperature continues increasing.

#### 4. True reverse current blocking function(Option)

This device has built-in True reverse current blocking circuit (TRCB) to block reverse current from VOUT to VIN regardless of output MOSFET ON/OFF condition. (Full-Time Reverse Current Protection)

#### 5. Under-voltage Lockout function(Option)

This device has a built-in Under-voltage Lockout Circuit to turn off switch if VIN drops below UVLO. This circuit has hysteresis and UVLO is released when VIN exceeds threshold.

#### 6. Instructions and directions for use

This device has a built-in several functions, but these does not assure for the suppression of uprising device operation. In use of these products, please read through and understand dissipation idea for absolute maximum ratings from the above mention or our 'Semiconductor Reliability Handbook'. Then use these products under absolute maximum ratings in any condition. Furthermore, Toshiba recommend inserting failsafe system into the design.



### 7. Power Dissipation

Power dissipation is measured on the board condition shown below.

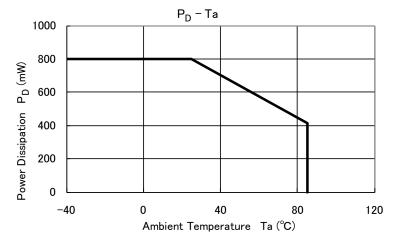
[The Board Condition]

Board material: Glass epoxy (FR4)

Board dimension: 40mm x 40mm (both sides of board), t=1.6mm

Metal pattern ratio: a surface approximately 50%, the reverse side approximately 50%

Through hole: diameter 0.5mm x 28

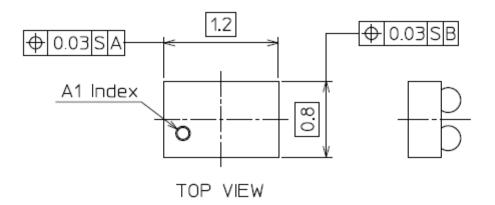


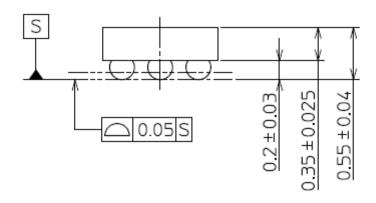
Please allow sufficient margin when designing a board pattern to fit the expected power dissipation. Also take into consideration the ambient temperature, input voltage, output current etc and applying the appropriate derating for allowable power dissipation during operation.

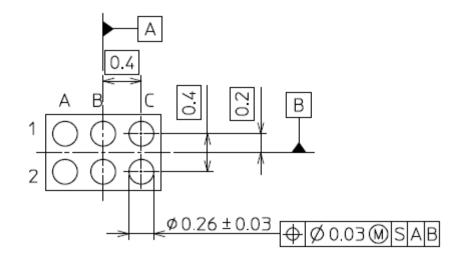
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## Package dimension

Unit: mm





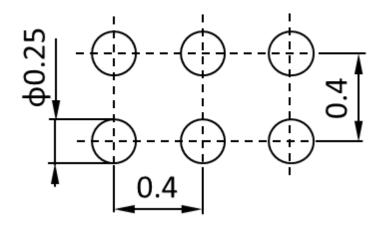


BOTTOM VIEW

Weight: 1 mg (typ.)

Land pattern dimensions (for reference only)

Unit: mm



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